

Key Features

Type TLRP Series

Up to 3 Watt at 70°C

12:06, 20:10, and 25:12 Packages Available

Low Inductance <5nH

AEC-Q200 Qualified

Sulfur Resistant unaffected by sulfur environments



TE Connectivity (TE) is pleased to offer these unique AEC-Q200 qualified High Power Metal Strip Resistors for Current Sensing positions. TLRP resistors have a special metal resistive element combined with suitable barrier layers beneath the solder to prolong terminal life. This model is particularly useful for power management along with DC-DC converting and charging applications, as well as adaptors within SWPS applications.

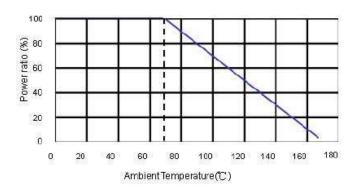
Characteristics - Electrical

Size	Power Rating	Re	TCR				
Size	@ 70°C	±0.5%	±1%	±5%	(PPM/°C)		
		8, 10, 12,	15, 20, 25, 3	0, 33, 40	±50		
1206	1W	3, 4, 5, 7,	8, 10, 12, 15,	, 20, 25, 30,	±75		
		33, 40	33, 40				
2010	1W	10, 15, 20, 30, 50, 68, 75, 100			±75		
2010	2W	10, 15, 20					
			7, 18, 20, 22, 2 , 50, 60, 68, 70 0, 120, 150, 18	, 75, 80, 82,	±25		
2512	2W & 3W	22, 25, 30	7, 8, 9, 10, 12, , 33, 35, 39, 40 , 80, 82, 90, 91 200	, 47, 50, 60,	±50 ±75		

Operating Temperature Range: -55 ~ 170°C

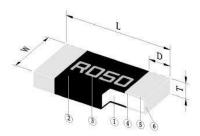
Operating Current = V(P/R), Operating Voltage = V(P*R)

Derating





Construction and Dimensions



Alloy Plate	4	Internal Electrode	
② Overcoat	(3)	Barrier Layer	
Marking	6	Solder Plating	

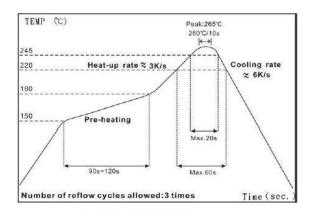
Туре	Size	L	W	T	D	
		mm	mm	mm	mm	
TLRP2B	1206	3.15±0.10	1.45±0.10	0.55±0.10	0.55±0.15	
TLRP2H	2010	5.00±0.10	2.40±0.15	0.60±0.10	0.80±0.20	
TLRP3A	2512	6.40±0.25	3.20±0.25	0.70±0.20	0.90±0.30	

Marking

Resistance (4 Digit)

Resistance	3mΩ	10mΩ	22mΩ	100mΩ
Codes	R003	R010	R022	R100

Solder Profile (Reflow)



IR Reflow Soldering

(1) Time of IR reflow soldering at maximum temperature point 260°C: 10s



Environmental Characteristics

Item	Requirement	Test Method
Temperature Coefficient of	As Spec.	IEC60115-1 4.8
Resistance (T.C.R.)		JIS-C-5201-1 4.8
		+25°C ~125°C, 25°C is the
		reference temperature
Short Time Overload	±1.0%	IEC60115-1 4.13
		JIS-C-5201-1 4.13
		5*rated power for 5 seconds
Insulation Resistance	≥10G	IEC60115-1 4.6
		JIS-C-5201-1 4.13
		100V DC for 1 minute
Endurance	±1.0%	IEC60115-1 4.25
		JIS-C-5201-1 4.25.1
		70±2°C, rated power for 1000 hrs
		with 1.5 hrs "ON" and 0.5 hr "OFF"
		MIL-STD-202 Method 108
		Condition D Steady State TA=125°C
		at derated power.
		Measurement at 24±4 hours after
		test conclusion.
Biased Humidity	±1.0%	MIL-STD-202 Method 103
		1000 hrs 85°C/85%RH 10% of
		operating power
Dry Heat	±1.0%	IEC60115-1 4.23.2
,		JIS-C-5201-1 4.23.2
		MIL-STD-202 Method 108
		at +170°C for 1000 hrs
Resistance to Solvents	No visible damage on	MIL-STD-202 Method 215
	appearance and	Note: Add Aqueous wash chemical
	marking.	- OKEM Clean or equivalent.
		Do not use banned solvents.
Mechanical Shock	±1.0%	MIL-STD-202 Method 213
		Wave Form: Tolerance for half sine
		shock pulse.
		Peak value is 100g's. Normal
		duration(D) is 6.
Vibration	±1.0%	MIL-STD-202 Method 204
		5g's for 20 min., 12 cycles each of
		3 orientations.
		Note: Use 8"X5" PCB .031" thick 7
		secure points on one long side and
		2 secure points at corners of
		opposite sides. Parts mounted
		within 2" from any secure point.
		Test from 10-2000 Hz.
ESD	±1.0%	AEC-Q200-002
		Human body model, 2KV. (DC =
		Direct Contact Discharge)
Flammability	V-0	UL-94
,		50W (20 mm) Vertical Burning
		Test. Electrical test not required.
	1	rest. Electrical test not required.



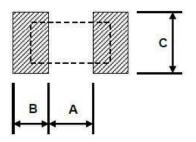
Item	Requirement	Test Method
Flame Retardance	The following	AEC-Q200-001
	phenomena cannot	Assemble the sample on the test
	occur during the	board, perform functional test
	experiment:	before flame retardant test to
	(1)A flame over 3.0	ensure no damage to the sample.
	seconds duration.	The test environment is 22±5 °C
	(2)An explosion.	still air, from 9.0 to 32.0 VDC
	(3)A temperature	(current clamped up to 500A),
	above 350°C	increase the voltages at the rate of
	sustained for over 10	1.0 VDC per hour until the end of
	seconds	the experiment.
Bending Strength	±1.0%	JIS-C-5201-1 4.33
		IEC-60115-1 4.33
		AEC-Q200-005
		Bending width 2mm once for 5
		seconds
Terminal Strength (SMD)	Not broken	AEC-Q200-006
		Force of 1.8kg for 60 seconds.
Solderability	95% min. coverage	JIS-C-5201-1 4.17
		IEC-60115-1 4.17
		J-STD-002
		245±5°C for 3seconds
Resistance to Soldering	±0.5%	JIS-C-5201-1 4.18
Heat		IEC-60115-1 4.18
		MIL-STD-202 Method 210
		260±5°C for 10 seconds
Rapid Change of	±1.0%	JIS-C-5201-1 4.19
Temperature		IEC-60115-1 4.19
		-55°C to +155°C, 5 cycles
Temperature Cycling	±1.0%	JESD22 Method JA-104
		1000 cycles (-55°C to +125°C,
		Dwell 30 minutes, transition time
		within 1 minute). Measurement at
		24±4 hours after test conclusion.
Low Temperature Storage	±1.0%	IEC60115-1 4.23.4
		JIS-C-5201-1 4.23.4
		at -55°C for 2hrs

RCWV (Rated Continuous Working Voltage)= $V(P^*R)$ or Max. Operating Voltage whichever is lower.

Storage Temperature: 15~28°C; Humidity < 80%RH



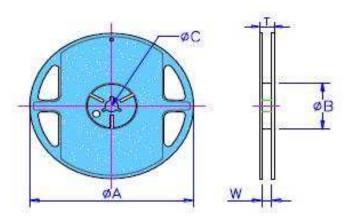
Recommended Land Pattern



Size	Α	В	С				
Size	(mm)	(mm)	(mm)				
1206	1.50	1.40	1.70				
2010	3.60	1.40	2.50±0.2				
2512	4.00	2.00 3.50					
*FR4 copper board, 100µm of copperpad thickness							

Packaging

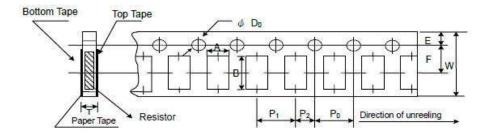
Reel Specifications & Packaging Quantity



Size	Resistance (mΩ	Tape / Qty	Tape width	Reel Dia.	ØA (mm) ±1.5	ØB (mm)	ØC (mm)	W (mm)	T (mm)
1206	3~40	Paper / 5K	8mm			60+1-0	13.0 ±0.2	9.0±0.5	12.5 ±0.5
2010	10~100	Embossed / 4K	12mm	7	170 F	60+1-0	13.0 ±0.5	13.0 ±0.5	15.5 ±0.5
2512	4~200	Embossed / 4K	12mm inch		178.5	60±1.0	13.0	13.0±1.	15.5
2512	3	Embossed / 2K	12mm			00±1.0	±0.5	0	±0.5

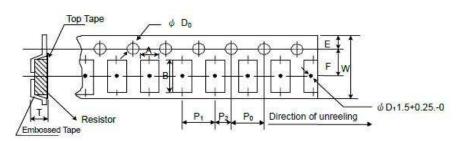


Paper Tape Specification



ĺ	Α	В	W	E	F	Po	P ₁	P ₂	ØD₀	Т
	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)
ſ	1.90±	3.50±	8.0±	1.75±	3.50±	4.00±	4.00±	2.00±	1.50	0.85±
	0.10	0.20	0.20	0.10	0.05	0.10	0.05	0.05	+0.1,-0	0.10

Embossed Plastic Tape Specification



	Α	В	W	E	F	Po	P ₁	P ₂	ØDο	Т
	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)
2010	2.80	5.5	12.0	0.75	5.5	4.00	4.00	2.00	1.5 +0.1	1.20+0
2010	±0.10	±0.10	±0.30	±0.10	±0.5	±0.10	±0.10	±0.05	-0	1.20+0
2512	3.50±	6.70±	12.0±	1.75±	5.5±	4.00±	4.00±	2.00±	1.50 +0.1	1.20+0
2512	0.10	0.10	0.30	0.10	0.05	0.10	0.10	0.05	-0	1.45±
3mΩ	0.10	0.10	0.50	0.10	0.03	0.10	0.10	0.03	-0	0.2

How To Order

TLRP	2B	10	E	R008	F	TD
Common Part	Size	*Power Rating	**TCR (PPM/°C)	Resistance Code	Tolerance	Packaging
TLRP – Ultra Low Ohm Metal Strip Resistor	2B – 1206 2H - 2010 3A – 2512	1.0 = 10 2.0 = 20 3.0 = 30	C = ±25 D = ±50 W = ±75 E = ±100	R003 - $3mΩ$ R020 - $20mΩ$ R10 - $0.1Ω$ (100 $mΩ$)	D = ±0.5% F = ±1% J = ±5%	TDG = 2000/Reel (2512 3mΩ) TE = 4000/Reel (2512) TD = 5000/Reel (1206)